# MBRA130LT3

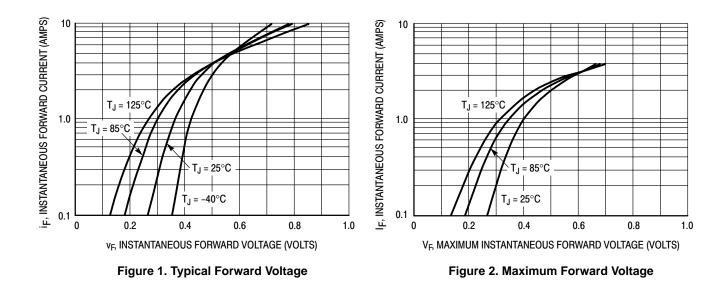
## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction-to-Lead (Note 1) Thermal Resistance — Junction-to-Ambient (Note 1)	$R_{ heta JL}$ $R_{ heta JA}$	35 86	°C/W

## **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 2)		V <sub>F</sub>	T <sub>J</sub> = 25°C	, <u> </u>	
see Figure 2	(I <sub>F</sub> = 1.0 A) (I <sub>F</sub> = 2.0 A)		0.41 0.47	0.35 0.43	
Maximum Instantaneous Reverse Current		I <sub>R</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	mA
see Figure 4	(V <sub>R</sub> = 30 V) (V <sub>R</sub> = 15 V)		1.0 0.4	25 12	

1. Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4. 2. Pulse Test: Pulse Width  $\leq$  250 µs, Duty Cycle  $\leq$  2.0%.



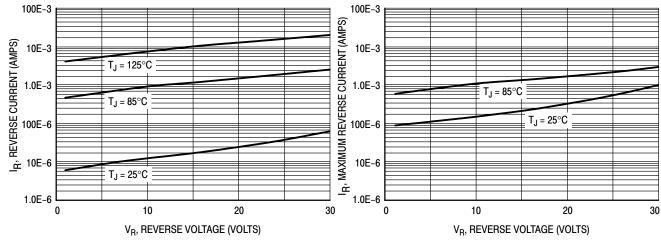


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

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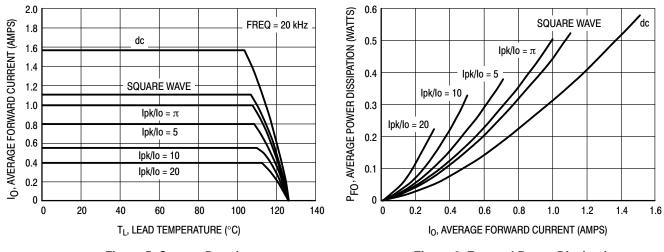
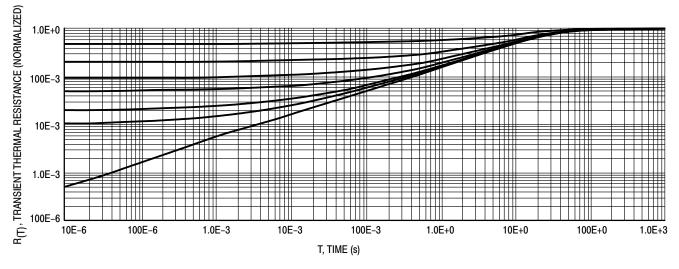




Figure 6. Forward Power Dissipation





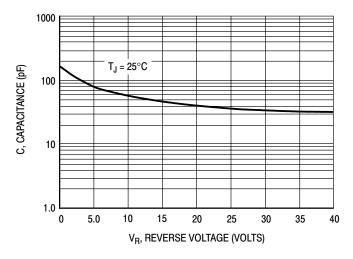
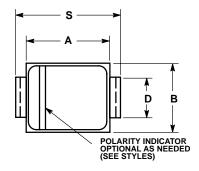


Figure 8. Capacitance

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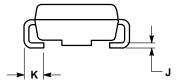
### PACKAGE DIMENSIONS

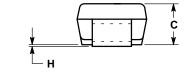
SMA CASE 403D-02 ISSUE B



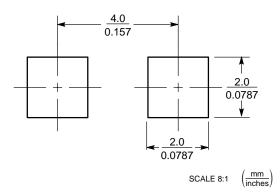
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 403D–01 OBSOLETE, NEW STANDARD IS 403D–02.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.090	0.115	2.29	2.92	
С	0.075	0.095	1.91	2.41	
D	0.050	0.064	1.27	1.63	
Н	0.002	0.006	0.05	0.15	
J	0.006	0.016	0.15	0.41	
Κ	0.030	0.060	0.76	1.52	
S	0.190	0.220	4.83	5.59	





**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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